

## Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- High Current Capability and Low Forward Voltage Drop
- **Lead Free Finish, RoHS Compliant (Note 4)**
- **"Green" Molding Compound (No Br, Sb)**
- **Qualified to AEC-Q101 Standards for High Reliability**

## Mechanical Data

- Case: PowerDI<sup>®</sup>123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: Cathode Band
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.01 grams (approximate)



Top View

## Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.  
 For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	30	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
RMS Reverse Voltage	$V_{R(RMS)}$	21	V
Average Forward Current @ $T_T = 121^\circ\text{C}$	$I_{F(AV)}$	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	$I_{FSM}$	50	A

## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	$P_D$	1.67	W
Power Dissipation (Note 2)	$P_D$	556	mW
Thermal Resistance Junction to Ambient (Note 1)	$R_{\theta JA}$	60	$^\circ\text{C/W}$
Thermal Resistance Junction to Ambient (Note 2)	$R_{\theta JA}$	180	$^\circ\text{C/W}$
Thermal Resistance Junction to Soldering (Note 3)	$R_{\theta JS}$	10	$^\circ\text{C/W}$
Operating Temperature Range	$T_J$	-40 to +125	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-40 to +150	$^\circ\text{C}$

## Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	30	—	—	V	$I_R = 1.0\text{mA}$
Forward Voltage	$V_F$	—	0.210	—	V	$I_F = 0.1\text{A}$
		—	0.310	—		$I_F = 1.0\text{A}$
		—	0.328	0.36		$I_F = 1.5\text{A}$
Leakage Current (Note 5)	$I_R$	—	0.260	—	mA	$V_R = 5\text{V}, T_A = 25^\circ\text{C}$
		—	—	1.0		$V_R = 30\text{V}, T_A = 25^\circ\text{C}$
Total Capacitance	$C_T$	—	76	—	pF	$V_R = 10\text{V}, f = 1.0\text{MHz}$

- Notes:
1. Part mounted on 2"x2" GETEK board with 1"x1" copper pad, 25% anode, 75% cathode.  $T_A = 25^\circ\text{C}$ .
  2. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  3. Theoretical  $R_{\theta JS}$  calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
  4. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at [http://www.diodes.com/products/lead\\_free.html](http://www.diodes.com/products/lead_free.html).
  5. Short duration pulse test used to minimize self-heating effect.

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DFLS130L

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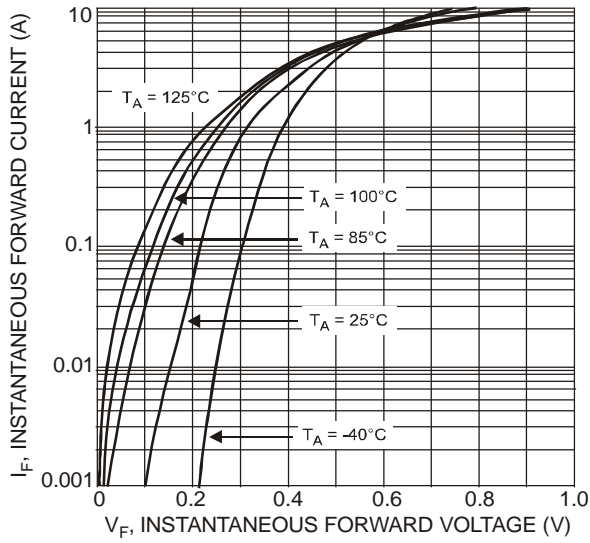


Fig. 1 Typical Forward Characteristics

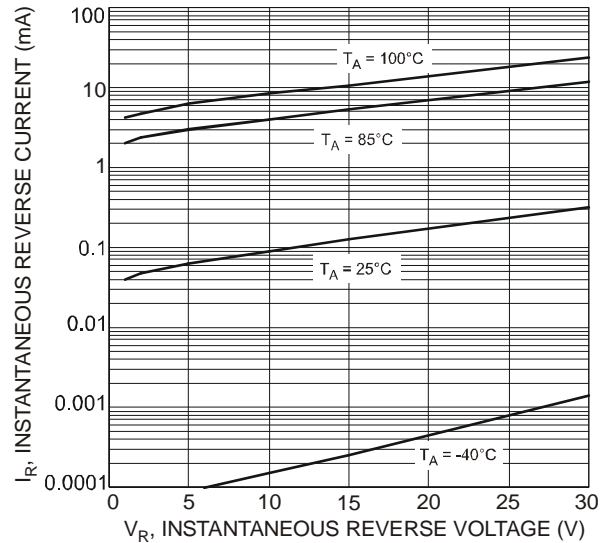


Fig. 2 Typical Reverse Characteristics

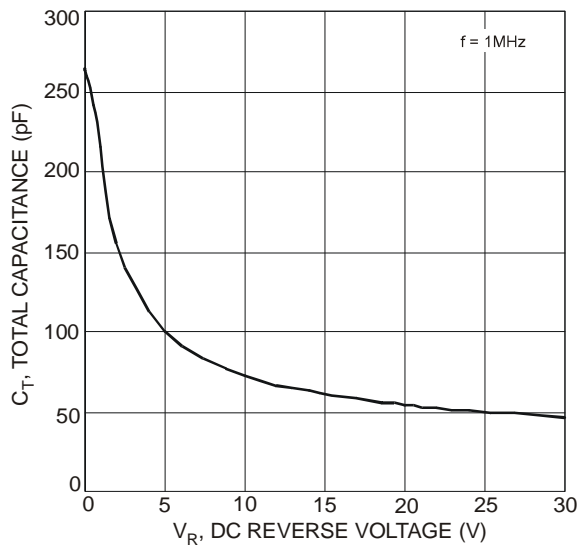


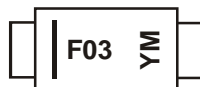
Fig. 3 Total Capacitance vs. Reverse Voltage

## Ordering Information (Note 6)

Part Number	Case	Packaging
DFLS130L-7	PowerDI <sup>®</sup> 123	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

## Marking Information



F03 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: R = 2004)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	2004	2005	2006	2007	2008	2009	2010	2011	2012			
Code	R	S	T	U	V	W	X	Y	Z			
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

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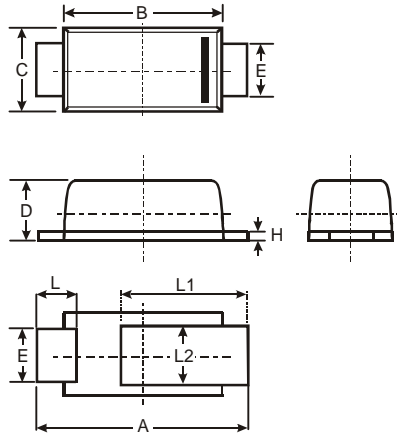
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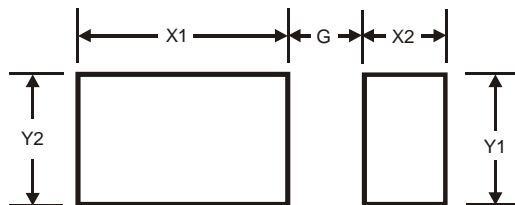
**Package Outline Dimensions**



PowerDI <sup>®</sup> 123			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.55	0.75	0.65
L1	1.80	2.20	2.00
L2	0.95	1.25	1.10

All Dimensions in mm

**Suggested Pad Layout**



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4

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